10/01 1, 120				
L Number		Search Text	DB	Time stamp
1	1878	((438/678) or (438/687)).CCLS.	USPAT;	2004/09/24 16:27
1			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
2	1688	(((438/678) or (438/687)).CCLS.) and	USPAT;	2004/09/24 16:27
2	1000	@ad<20021212	US-PGPUB;	2004/03/24 10.27
ļ ļ		944/20021212	EPO; JPO;	
			DERWENT;	
.			IBM TDB	
3	601	((((438/678) or (438/687)).CCLS.) and	USPAT;	2004/09/24 16:27
		@ad<20021212) and electroless	US-PGPUB;	
			EPO; JPO;	·
			DERWENT;	
			IBM_TDB	
4	510	(((((438/678) or (438/687)).CCLS.) and	USPAT;	2004/09/24 16:28
		@ad<20021212) and electroless) and (copper	US-PGPUB;	
		cu)	EPO; JPO;	
			DERWENT; IBM TDB	
_	443	((((((438/678) or (438/687)).CCLS.) and	USPAT;	2004/09/24 16:31
5	441	@ad<20021212) and electroless) and (copper	US-PGPUB;	2004/03/24 10:31
[cu)) and etch\$3	EPO; JPO;	
		Cu// unu Cecnys	DERWENT;	
			IBM TDB	
6	203	(((((((438/678) or (438/687)).CCLS.) and	USPAT;	2004/09/24 16:31
-		@ad<20021212) and electroless) and (copper	US-PGPUB;	l i
		cu)) and etch\$3) and (gold au)	EPO; JPO;	
			DERWENT;	ĺ
			IBM_TDB	
-	7342		USPAT;	2004/09/24 16:27
		(29/846) or (29/852)).CCLS.	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
i _	6352	(((29/874) or (29/829) or (29/830) or	USPAT;	2004/09/23 13:23
_	0332	((29/846) or (29/852)).CCLS.) and	US-PGPUB;	
		@ad<20021212	EPO; JPO;	·
			DERWENT;	
	• •		IBM_TDB	
-	484		USPAT;	2004/09/23 13:24
		(29/846) or (29/852)).CCLS.) and	US-PGPUB;	
		@ad<20021212) and (electroless adj plat\$3)	EPO; JPO;	
			DERWENT; IBM TDB	
	410	((((((29/874) or (29/829) or (29/830) or	USPAT;	2004/09/23 13:24
-	412	(((((29/874) Of (29/852)) CCLS.) and	US-PGPUB;	2001, 03, 20 20121
		@ad<20021212) and (electroless adj plat\$3))	EPO; JPO;	
		and (copper cu)	DERWENT;	
		,	IBM_TDB	
-	342		USPAT;	2004/09/23 13:25
		(29/846) or (29/852)).CCLS.) and	US-PGPUB;	
		@ad<20021212) and (electroless adj plat\$3))	EPO; JPO;	
		and (copper cu)) and etch\$3	DERWENT;	
		(10/////00/00/)	IBM_TDB	2004/00/22 12:25
-	189		USPAT;	2004/09/23 13:25
		(29/846) or (29/852)).CCLS.) and	US-PGPUB; EPO; JPO;	
	Ī	<pre>@ad<20021212) and (electroless adj plat\$3)) and (copper cu)) and etch\$3) and (gold au)</pre>	DERWENT;	
		and (copper out) and econos, and (gord au)	IBM TDB	
-	150	((((((((29/874) or (29/829) or (29/830) or	USPAT;	2004/09/23 13:26
		(29/846) or (29/852)).CCLS.) and	US-PGPUB;	
		@ad<20021212) and (electroless adj plat\$3))	EPO; JPO;	
		and (copper cu)) and etch\$3) and (gold au))	DERWENT;	
		and (via through-hole)	IBM_TDB	
-	149		USPAT;	2004/09/23 13:31
		(29/846) or (29/852)).CCLS.) and	US-PGPUB;	
		<pre>@ad<20021212) and (electroless adj plat\$3)) and (copper cu)) and etch\$3) and (gold au))</pre>	EPO; JPO; DERWENT;	'
		and (copper cu)) and etch\$3) and (gold au/) and (via through-hole)) and (substrate board	IBM_TDB	
1		PCB PWB)		
L		1 CD END)	J	<u> </u>